## A. Specification Paragraphs With Mark-ups to Show Changes Made

**The following are mark-ups to show changes made to paragraph(s) starting at page 11, line 32 and ending at page 12, line 31:**

Referring to Fig. 4, there is shown a radio frequency plasma display panel (RFPDP) according to an embodiment of the present invention. The RFPDP includes dielectric patterns 34, an address electrode 36 and a first lower dielectric layer 38 that are disposed on a rear substrate 32, and a scanning electrode 42 crossing the address electrode 36 on the first lower dielectric layer 38. Each of the [electric] dielectric patterns 34 is thin at each side thereof and is convex at the center thereof. These dielectric patterns 34 are patterned in a stripe shape on the rear substrate 32 in such a manner to be spaced by a desired distance. The address electrode 36 is formed into a uniform thickness on the rear substrate 32 provided with the dielectric patterns 34. Thus, the address electrode 36 is formed into a wave shape having lands and grooves. The first lower dielectric layer 38 covers the address electrode 36. The groove portion of the first lower dielectric layer 38 has a gentler slope than the groove portion of the address electrode 36. The scanning electrode 42 is formed on the gentle groove portion of the first lower dielectric layer 38 to be perpendicular to the address electrode 36. The second lower dielectric layer 40 is formed on the first lower dielectric layer 38 in such a manner to have an even surface and covers the scanning electrode 42. The thickness t1 of the first and second lower dielectric layers 38 and 40 covered on the land portion of the address electrode 36 is thinner than that of the dielectric layers 16 and 20 shown in Fig. 2. Since a voltage loss is reduced to such an extent that the lower

dielectric layers 38 and 40 become thin, a voltage level of a writing voltage applied between the address electrode 36 and the scanning electrode 42 can be lowered.

**The following are mark-ups to show changes made to paragraph(s) starting at page 16, line 4 and ending at page 16, line 21:**

Fig. 7 shows a lower plate of a RFPDP according to a third embodiment of the present invention. Referring to Fig. 7, the RFPDP includes an address electrode 74 and a scanning electrode 78 that crosses each other on a rear substrate 72, a dielectric pattern 76 provided at an intersection between the address electrode 74 and the scanning electrode 78, and a lower dielectric layer 80 coated entirely on the rear substrate 72. The dielectric pattern 46 has a stripe shape or a line shape, and is formed in a direction perpendicular to the address electrode 74 to serve as [a] an insulating layer between the address electrode 74 and the scanning electrode 78. The scanning electrode 78 is formed along the dielectric pattern 76 thereon. The lower dielectric layer 80 covers the address electrode 74, the dielectric pattern 76 and the scanning electrode 78. A protective film 82 is entirely formed on the lower dielectric layer 80, and barrier ribs [82] 84 are formed on the protective film 82.

**The following are markups to show changes made to paragraph(s) starting at page 20, line 21 and ending at page 21, line nine:**

Figs. 11A to 11D shows a method of fabricating a lower plate of the RFPDP in Fig. 9 step by step. Referring to Fig. 11A, the address electrode 104 is patterned in a line shape on the rear substrate 102 by means of the screen printing process or the photolithography. A mask pattern provided with a square pattern at a position corresponding to the center of the cell is aligned on the substrate 102 provided with the address electrode 104, and thereafter a dielectric material is coated thereon. Then, the dielectric pattern 106 with a square island shape as shown in Fig. 11B is formed at the center of the cell, that is, at a position corresponding to an intersection between the address electrode 104 and the scanning electrode 108. Subsequently, in Fig. 11C, the scanning electrode 108 is formed in a line shape on the dielectric pattern 106 in such a manner to cross the address electrode 104. On the rear substrate 102 provided with the address electrode 104 and the scanning electrode 108, as shown in Fig. 11D, the lower dielectric layer 110 is entirely coated. Finally, the protective film [112] <u>114</u> is entirely deposited on the lower dielectric layer 110.

B. Clean Specification Changes

**Please replace paragraph(s) starting at page 11, line 32 and ending at page 12, line 31 with the following paragraph(s):**

Referring to Fig. 4, there is shown a radio frequency plasma display panel (RFPDP) according to an embodiment of the present invention. The RFPDP includes dielectric patterns 34, an address electrode 36 and a first lower dielectric layer 38 that are disposed on a rear substrate 32, and a scanning electrode 42 crossing the address electrode 36 on the first lower dielectric layer 38. Each of the dielectric patterns 34 is thin at each side thereof and is convex at the center thereof. These dielectric patterns 34 are patterned in a stripe shape on the rear substrate 32 in such a manner to be spaced by a desired distance. The address electrode 36 is formed into a uniform thickness on the rear substrate 32 provided with the dielectric patterns 34. Thus, the address electrode 36 is formed into a wave shape having lands and grooves. The first lower dielectric layer 38 covers the address electrode 36. The groove portion of the first lower dielectric layer 38 has a gentler slope than the groove portion of the address electrode 36. The scanning electrode 42 is formed on the gentle groove portion of the first lower dielectric layer 38 to be perpendicular to the address electrode 36. The second lower dielectric layer 40 is formed on the first lower dielectric layer 38 in such a manner to have an even surface and covers the scanning electrode 42. The thickness t1 of the first and second lower dielectric layers 38 and 40 covered on the land portion of the address electrode 36 is thinner than that of the dielectric layers 16 and 20 shown in Fig. 2. Since a voltage loss is reduced to such an extent that the lower

dielectric layers 38 and 40 become thin, a voltage level of a writing voltage applied between the address electrode 36 and the scanning electrode 42 can be lowered.

**Please replace paragraph(s) starting at page 16, line 4 and ending at page 16, line 21 with the following paragraph(s):**

Fig. 7 shows a lower plate of a RFPDP according to a third embodiment of the present invention. Referring to Fig. 7, the RFPDP includes an address electrode 74 and a scanning electrode 78 that crosses each other on a rear substrate 72, a dielectric pattern 76 provided at an intersection between the address electrode 74 and the scanning electrode 78, and a lower dielectric layer 80 coated entirely on the rear substrate 72. The dielectric pattern 46 has a stripe shape or a line shape, and is formed in a direction perpendicular to the address electrode 74 to serve as an insulating layer between the address electrode 74 and the scanning electrode 78. The scanning electrode 78 is formed along the dielectric pattern 76 thereon. The lower dielectric layer 80 covers the address electrode 74, the dielectric pattern 76 and the scanning electrode 78. A protective film 82 is entirely formed on the lower dielectric layer 80, and barrier ribs 84 are formed on the protective film 82.

**Please replace paragraph(s) starting at page 20, line 21 and ending at page 21, line 9 with the following paragraph(s):**

Figs. 11A to 11D shows a method of fabricating a lower plate of the RFPDP in Fig. 9 step by step. Referring to Fig. 11A, the address electrode 104 is patterned in a line shape on the rear substrate 102 by means of the screen printing process or the photolithography. A mask pattern provided with a square pattern at a position corresponding to the center of the cell is aligned on the substrate 102 provided with the address electrode 104, and thereafter a dielectric material is coated thereon. Then, the dielectric pattern 106 with a square island shape as shown in Fig. 11B is formed at the center of the cell, that is, at a position corresponding to an intersection between the address electrode 104 and the scanning electrode 108. Subsequently, in Fig. 11C, the scanning electrode 108 is formed in a line shape on the dielectric pattern 106 in such a manner to cross the address electrode 104. On the rear substrate 102 provided with the address electrode 104 and the scanning electrode 108, as shown in Fig. 11D, the lower dielectric layer 110 is entirely coated. Finally, the protective film 114 is entirely deposited on the lower dielectric layer 110.